# 506786604 07/27/2021

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6833423

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
TETSUYA KOSUGI	03/03/2021
TAKUTO SHOJI	03/03/2021
SHINOBU SUGIURA	03/04/2021
YUYA YOSHIMURA	03/23/2021

## **RECEIVING PARTY DATA**

Name:	KOKUSAI ELECTRIC CORPORATION
Street Address:	3-4, KANDAKAJI-CHO, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	29773972

## **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Email:** mmcgrady@fitcheven.com

Correspondent Name: FITCH, EVEN, TABIN, AND FLANNERY
Address Line 1: 120 SOUTH LASALLE STREET, SUITE 2100

Address Line 4: CHICAGO, ILLINOIS 60603

ATTORNEY DOCKET NUMBER:	20372-152004-US
NAME OF SUBMITTER:	ALAN E. SCHIAVELLI
SIGNATURE:	/Alan E. Schiavelli/
DATE SIGNED:	07/27/2021

# **Total Attachments: 4**

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> PATENT REEL: 056990 FRAME: 0703

506786604

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by KOKUSAI ELECTRIC CORPORATION a corporation organized under the laws of Japan,

located at 3-4, Kandakaji-cho, Chiyoda-ku, Tokyo, Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said KOKUSAI ELECTRIC CORPORATION its successor and assigns, all my right, title and interest, in and for the United States of America, in and to

### CEILING HEATER FOR SUBSTRATE PROCESSING APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said KOKUSAI ELECTRIC CORPORATION

its successor, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made:

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said KOKUSAI ELECTRIC CORPORATION

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

	(発明者フルネームサイン)	(署名日)
1)	Shinobu SUGIURA	
2) <u>uya Kosugi /</u>	Tetsuya KOSUGI	Mar 3 ,2021
3)	Yuya YOSHIMURA	
4)	Takuto SHOJI	
5)		
6)		
7)		
8)		
9)		
10)		

PATENT REEL: 056990 FRAME: 0704

**Date Signed** 

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Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)	
1)	Shinobu SUGIURA		
2)	Tetsuya KOSUGI		
3)	Yuya YOSHIMURA		
4)	/ Takuto Shoji / Takuto SHOJI	Mar 3, 2021	
5)			
6)			
7)			
8)			
9)			
10)			

PATENT REEL: 056990 FRAME: 0705

(譲渡証)

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Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

	(発明者フルネームサイン)		(署名日)	
1)	/Shinobu Sugiura /	Shinobu SUGIURA	Mar 4,2021	
2)	***************************************	Tetsuya KOSUGI		
3)		Yuya YOSHIMURA		
4)		Takuto SHOJI		manana
5)				
7)			**************************************	
				*****
8)				monon
9)				
(O)				

PATENT REEL: 056990 FRAME: 0706

**Date Signed** 

(譲渡証)

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RECORDED: 07/27/2021

INVENTOR(S) (発明者フルネームサイン)		Date Signed (署名日)	
1)	Shinobu SUGIURA		
2)	Tetsuya KOSUGI		
3) <u>ya Yoshimura</u>	/ Yuya YOSHIMURA	Mar 23, 2021	
4)	Takuto SHOJI		
5)			
7)			
8)			
(0)			

PATENT REEL: 056990 FRAME: 0707